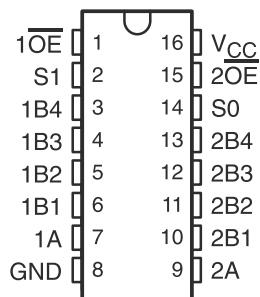


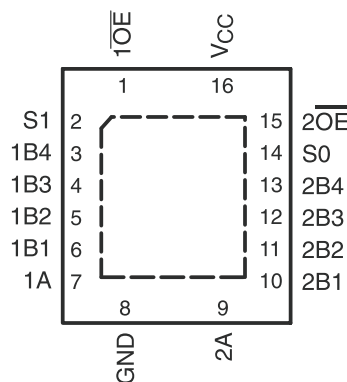
FEATURES

- SN74CBT3253C Functionally Identical to Industry-Standard '3253 Function
- Undershoot Protection for Off-Isolation on A and B Ports up to -2 V
- Bidirectional Data Flow, With Near-Zero Propagation Delay
- Low ON-State Resistance (r_{on}) Characteristics ($r_{on} = 3\ \Omega$ Typical)
- Low Input/Output Capacitance Minimizes Loading and Signal Distortion ($C_{io(OFF)} = 5.5\ \text{pF}$ Typical)
- Data and Control Inputs Provide Undershoot Clamp Diodes
- Low Power Consumption ($I_{CC} = 3\ \mu\text{A}$ Max)
- V_{CC} Operating Range From 4 V to 5.5 V
- Data I/Os Support 0 to 5-V Signaling Levels (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V, 5 V)
- Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)
- Supports I²C Bus Expansion
- Supports Both Digital and Analog Applications: USB Interface, Bus Isolation, Low-Distortion Signal Gating

D, DB, DBQ, OR PW PACKAGE
(TOP VIEW)



RGY PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The SN74CBT3253C is a high-speed TTL-compatible FET multiplexer/demultiplexer with low ON-state resistance (r_{on}), allowing for minimal propagation delay. Active Undershoot-Protection Circuitry on the A and B ports of the SN74CBT3253C provides protection for undershoot up to -2 V by sensing an undershoot event and ensuring that the switch remains in the proper OFF state.

The SN74CBT3253C is organized as two 1-of-4 multiplexer/demultiplexers with separate output-enable ($1\overline{OE}$, $2\overline{OE}$) inputs. The select (S0, S1) inputs control the data path of each multiplexer/demultiplexer. When $\overline{OE}$ is low, the associated multiplexer/demultiplexer is enabled, and the A port is connected to the B port, allowing bidirectional data flow between ports. When $\overline{OE}$ is high, the associated multiplexer/demultiplexer is disabled, and a high-impedance state exists between the A and B ports.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74CBT3253C
DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER
5-V BUS SWITCH WITH -2-V UNDERSHOOT PROTECTION

SCDS123B–JULY 2003–REVISED JANUARY 2007

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

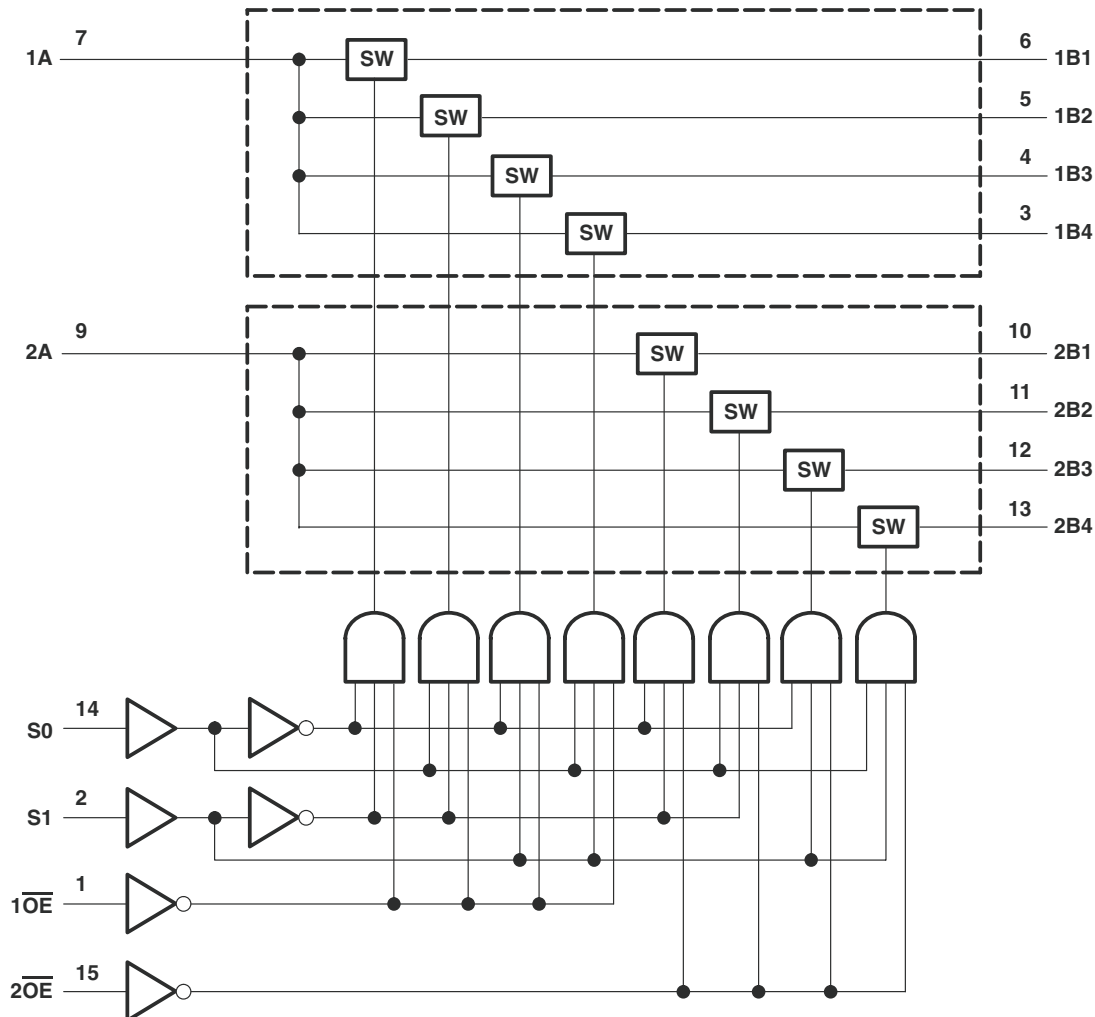
T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Reel of 1000	SN74CBT3253CRGYR	CU253C
	SOIC – D	Tube of 40	SN74CBT3253CD	CBT3253C
		Reel of 2500	SN74CBT3253CDR	
	SSOP – DB	Tube of 80	SN74CBT3253CDB	CU253C
		Reel of 2000	SN74CBT3253CDBR	
	SSOP (QSOP) – DBQ	Reel of 2500	SN74CBT3253CDBQR	CU253C
	TSSOP – PW	Tube of 90	SN74CBT3253CPW	CU253C
		Reel of 2000	SN74CBT3253CPWR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

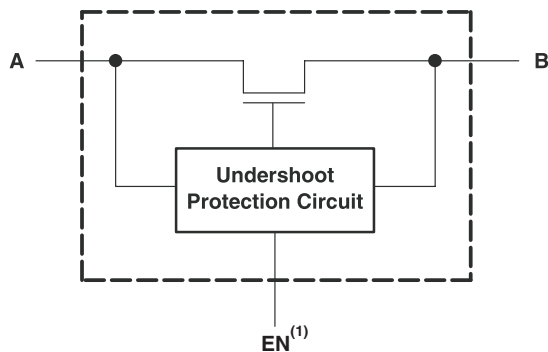
FUNCTION TABLE (each multiplexer/demultiplexer)

INPUTS			INPUT/OUTPUT A	FUNCTION
$\overline{OE}$	S1	S0		
L	L	L	B1	A port = B1 port
L	L	H	B2	A port = B2 port
L	H	L	B3	A port = B3 port
L	H	H	B4	A port = B4 port
H	X	X	X	Disconnect

LOGIC DIAGRAM (POSITIVE LOGIC)



SIMPLIFIED SCHEMATIC, EACH FET SWITCH (SW)



(1) EN is the internal enable signal applied to the switch.

SN74CBT3253C

DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

5-V BUS SWITCH WITH -2-V UNDERSHOOT PROTECTION

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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		-0.5	7	V
V_{IN}	Control input voltage range ⁽²⁾⁽³⁾		-0.5	7	V
$V_{I/O}$	Switch I/O voltage range ⁽²⁾⁽³⁾⁽⁴⁾		-0.5	7	V
I_{IK}	Control input clamp current	$V_{IN} < 0$		-50	mA
$I_{I/OK}$	I/O port clamp current	$V_{I/O} < 0$		-50	mA
$I_{I/O}$	ON-state switch current ⁽⁵⁾			±128	mA
	Continuous current through V_{CC} or GND terminals			±100	mA
θ_{JA}	Package thermal impedance	D package ⁽⁶⁾		73	°C/W
		DB package ⁽⁶⁾		82	
		DBQ package ⁽⁶⁾		90	
		PW package ⁽⁶⁾		108	
		RGY package ⁽⁷⁾		39	
T_{stg}	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4) V_I and V_O are used to denote specific conditions for $V_{I/O}$.
- (5) I_I and I_O are used to denote specific conditions for $I_{I/O}$.
- (6) The package thermal impedance is calculated in accordance with JESD 51-7.
- (7) The package thermal impedance is calculated in accordance with JESD 51-5.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage		4	5.5	V
V_{IH}	High-level control input voltage		2	5.5	V
V_{IL}	Low-level control input voltage		0	0.8	V
$V_{I/O}$	Data input/output voltage		0	5.5	V
T_A	Operating free-air temperature		-40	85	°C

- (1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics⁽¹⁾

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽²⁾	MAX	UNIT
V_{IK}	Control inputs	$V_{CC} = 4.5\text{ V}$,	$I_{IN} = -18\text{ mA}$			-1.8	V
V_{IKU}	Data inputs	$V_{CC} = 5\text{ V}$,	$0\text{ mA} > I_I \geq -50\text{ mA}$, $V_{IN} = V_{CC}$ or GND, Switch OFF			-2	V
I_{IN}	Control inputs	$V_{CC} = 5.5\text{ V}$,	$V_{IN} = V_{CC}$ or GND			± 1	μA
I_{OZ} ⁽³⁾		$V_{CC} = 5.5\text{ V}$,	$V_O = 0$ to 5.5 V , $V_I = 0$, Switch OFF, $V_{IN} = V_{CC}$ or GND			± 10	μA
I_{off}		$V_{CC} = 0$,	$V_O = 0$ to 5.5 V , $V_I = 0$			10	μA
I_{CC}		$V_{CC} = 5.5\text{ V}$,	$I_{I/O} = 0$, $V_{IN} = V_{CC}$ or GND, Switch ON or OFF			3	μA
ΔI_{CC} ⁽⁴⁾	Control inputs	$V_{CC} = 5.5\text{ V}$,	One input at 3.4 V , Other inputs at V_{CC} or GND			2.5	mA
C_{in}	Control inputs	$V_{IN} = 3\text{ V}$ or 0			3.5		pF
$C_{io(OFF)}$	A port	$V_{I/O} = 3\text{ V}$ or 0,	Switch OFF, $V_{IN} = V_{CC}$ or GND		14		pF
	B port				5.5		
$C_{io(ON)}$		$V_{I/O} = 3\text{ V}$ or 0,	Switch ON, $V_{IN} = V_{CC}$ or GND		22		pF
r_{on} ⁽⁵⁾		$V_{CC} = 4\text{ V}$, TYP at $V_{CC} = 4\text{ V}$	$V_I = 2.4\text{ V}$, $I_O = -15\text{ mA}$		8	12	Ω
		$V_{CC} = 4.5\text{ V}$	$V_I = 0$, $I_O = 64\text{ mA}$		3	6	
			$I_O = 30\text{ mA}$		3	6	
			$V_I = 2.4\text{ V}$, $I_O = -15\text{ mA}$		5	10	

(1) V_{IN} and I_{IN} refer to control inputs. V_I , V_O , I_I , and I_O refer to data pins.

(2) All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

(4) This is the increase in supply current for each input that is at the specified voltage level, rather than V_{CC} or GND

(5) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V}$ $\pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
t_{pd} ⁽¹⁾	A or B	B or A		0.24		0.15	ns
$t_{pd(s)}$	S	A		5.9	1.5	5.4	ns
t_{en}	S	B		6.2	1.5	5.8	ns
	$\overline{OE}$	A or B		5.7	1.5	5.3	
t_{dis}	S	B		6.2	1.5	5.8	ns
	$\overline{OE}$	A or B		5.7	1.5	5.3	

(1) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

SN74CBT3253C

DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

5-V BUS SWITCH WITH -2-V UNDERSHOOT PROTECTION

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Undershoot Characteristics

See [Figure 1](#) and [Figure 2](#)

PARAMETER	TEST CONDITIONS			MIN	TYP ⁽¹⁾	MAX	UNIT
V_{OUTU}	$V_{CC} = 5.5 \text{ V}$	Switch OFF,	$V_{IN} = V_{CC}$ or GND	2	$V_{OH} - 0.3$		V

(1) All typical values are at $V_{CC} = 5 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

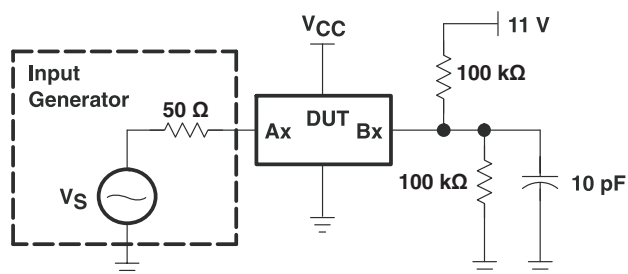


Figure 1. Device Test Setup

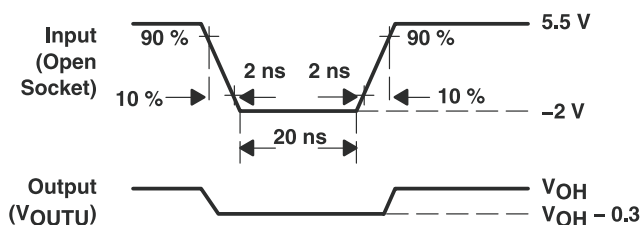
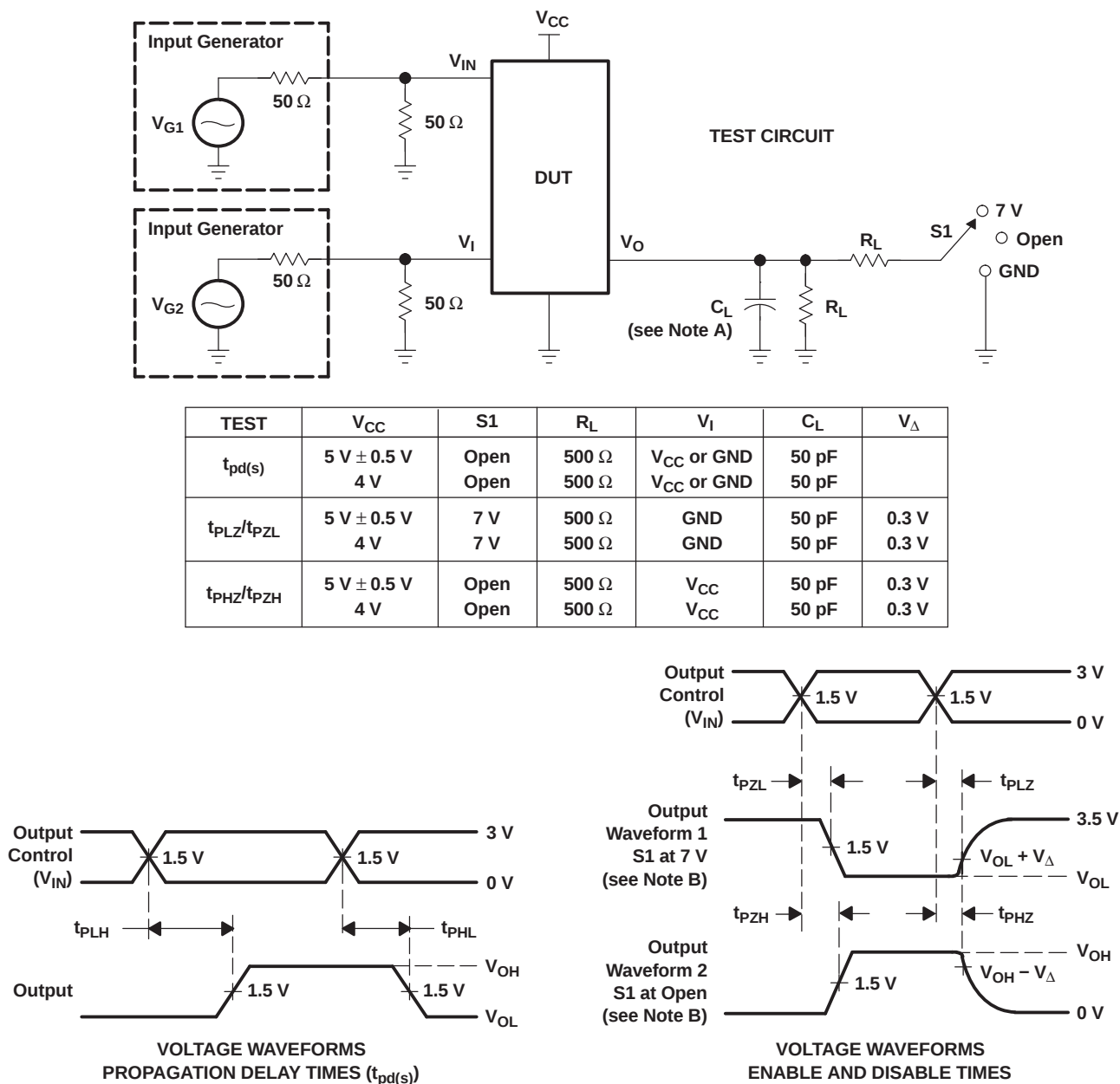


Figure 2. Transient Input Voltage (V_i) and Output Voltage (V_{OUTU}) Waveforms (Switch OFF)

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - t_{PZL} and t_{PZH} are the same as t_{en}.
 - t_{PLH} and t_{PHL} are the same as t_{pd(s)}. The t_{pd} propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
 - All parameters and waveforms are not applicable to all devices.

Figure 3. Test Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74CBT3253CD	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3253C
SN74CBT3253CD.B	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3253C
SN74CBT3253CDBQR	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU253C
SN74CBT3253CDBQR.B	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU253C
SN74CBT3253CDBR	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU253C
SN74CBT3253CDBR.B	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU253C
SN74CBT3253CDR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3253C
SN74CBT3253CDR.B	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3253C
SN74CBT3253CDRE4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3253C
SN74CBT3253CDRG4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3253C
SN74CBT3253CPW	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU253C
SN74CBT3253CPW.B	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU253C
SN74CBT3253CPWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU253C
SN74CBT3253CPWR.B	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU253C
SN74CBT3253CRGYR	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU253C
SN74CBT3253CRGYR.B	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU253C

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT3253CDBQR	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
SN74CBT3253CDBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74CBT3253CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74CBT3253CPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CBT3253CRGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT3253CDBQR	SSOP	DBQ	16	2500	353.0	353.0	32.0
SN74CBT3253CDBR	SSOP	DB	16	2000	353.0	353.0	32.0
SN74CBT3253CDR	SOIC	D	16	2500	353.0	353.0	32.0
SN74CBT3253CPWR	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74CBT3253CRGYR	VQFN	RGY	16	3000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74CBT3253CD	D	SOIC	16	40	507	8	3940	4.32
SN74CBT3253CD.B	D	SOIC	16	40	507	8	3940	4.32
SN74CBT3253CPW	PW	TSSOP	16	90	530	10.2	3600	3.5
SN74CBT3253CPW.B	PW	TSSOP	16	90	530	10.2	3600	3.5

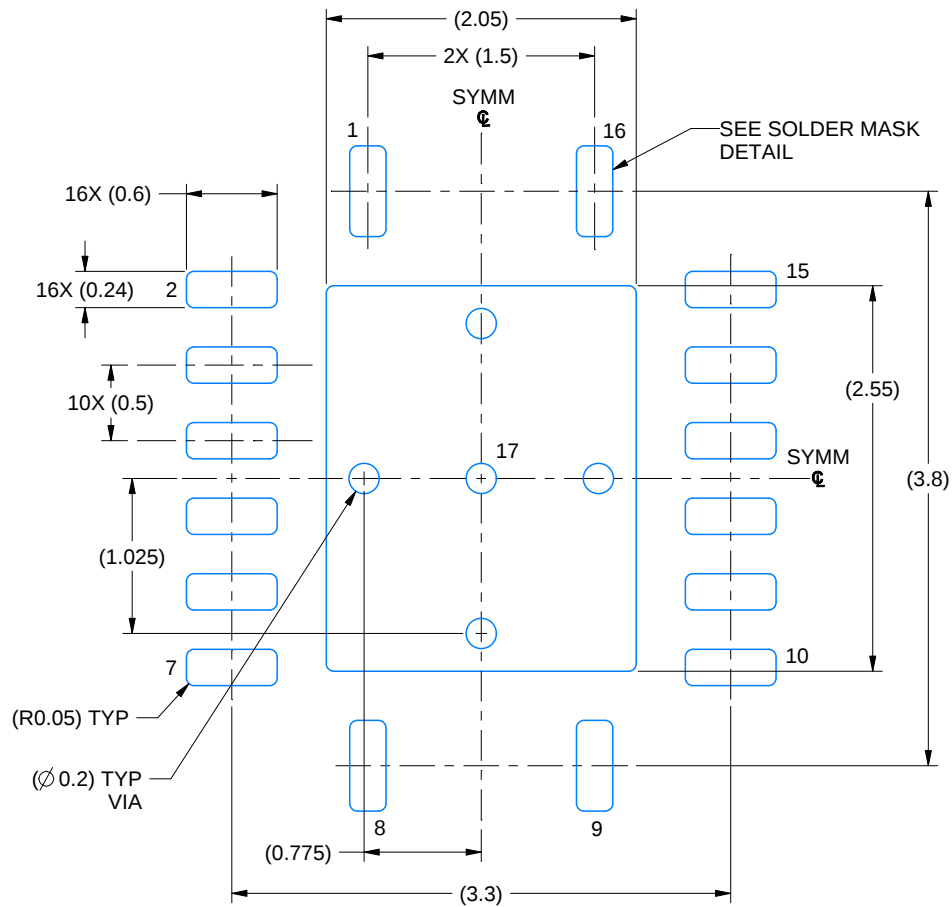
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

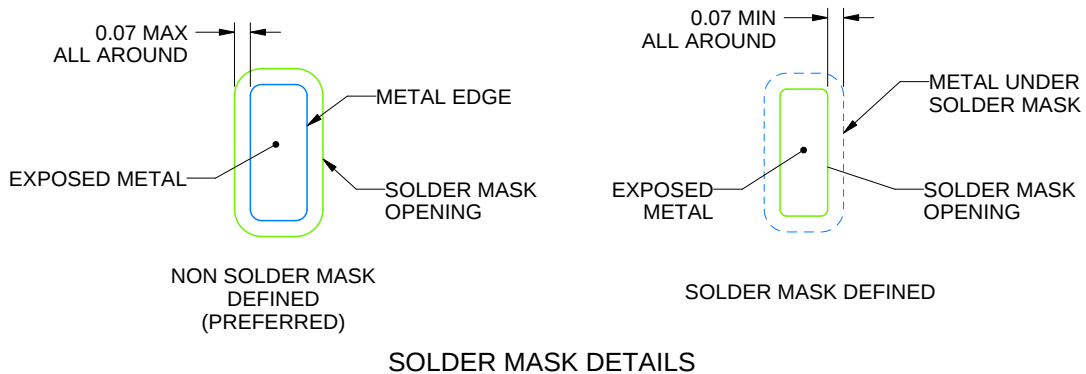
RGY0016A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



4225140/A 07/2019

NOTES: (continued)

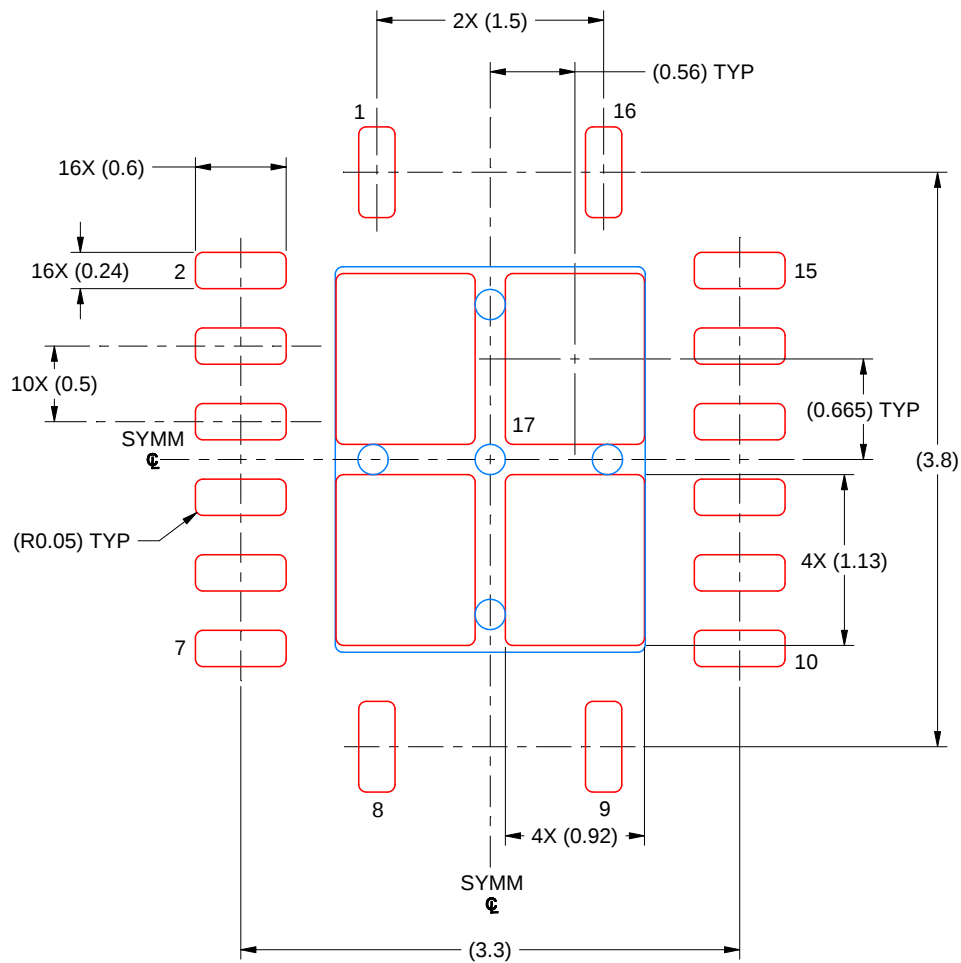
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RGY0016A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 17
80% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4225140/A 07/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

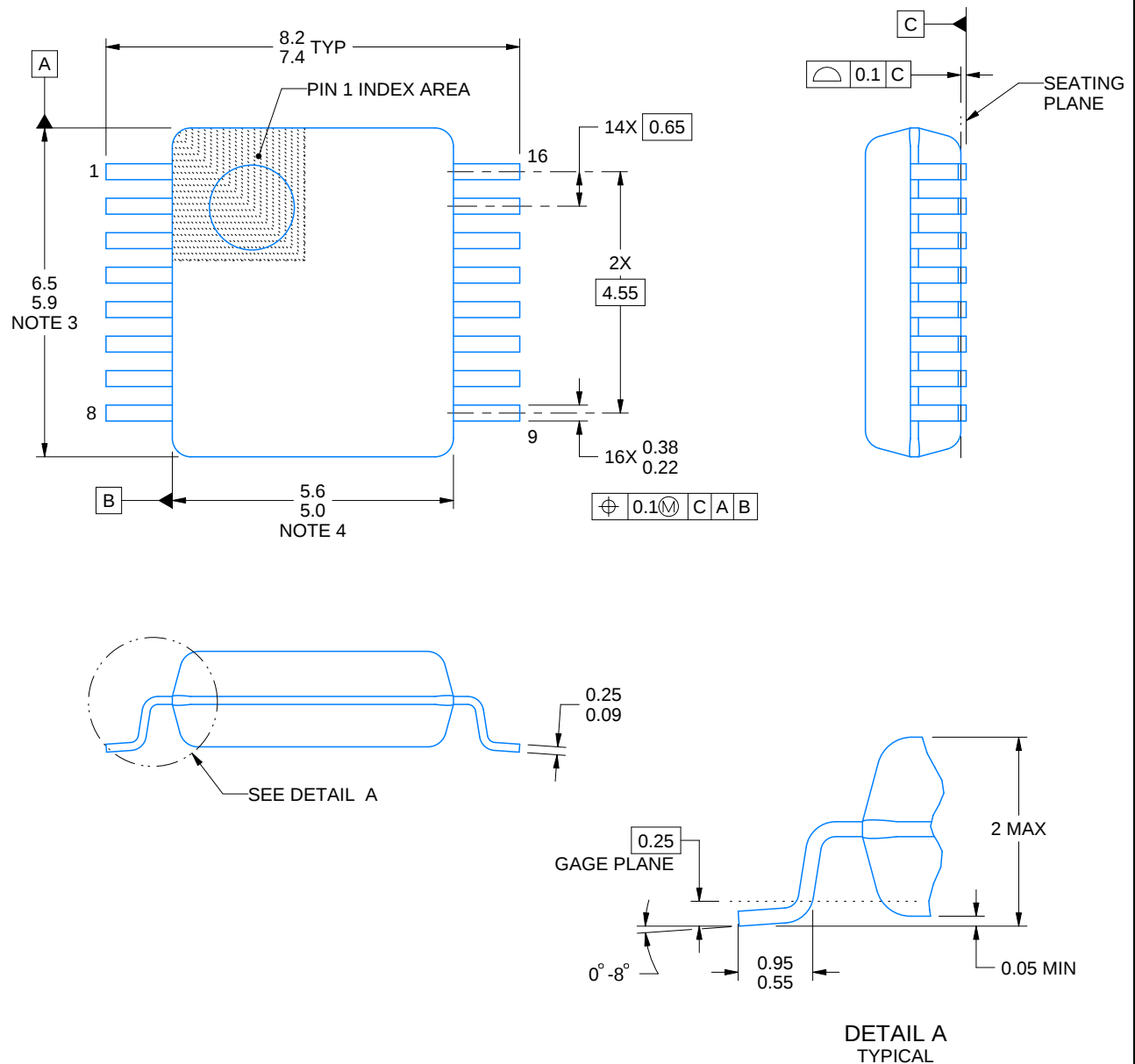
D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.



4220763/A 05/2022

NOTES:

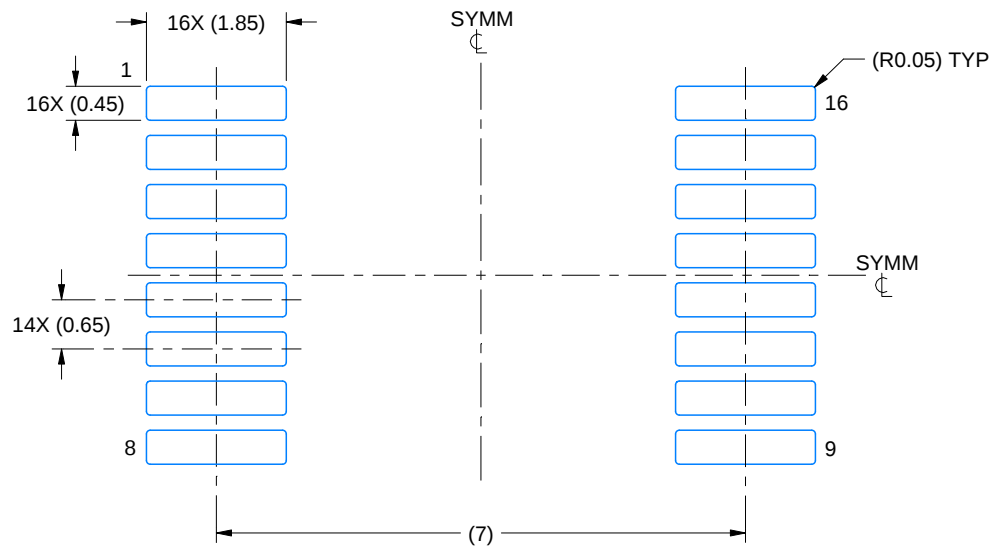
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

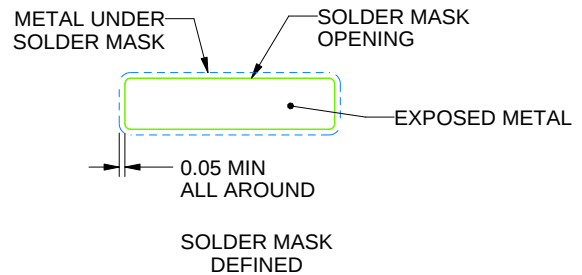
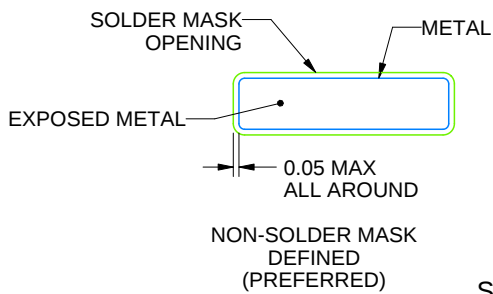
DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220763/A 05/2022

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

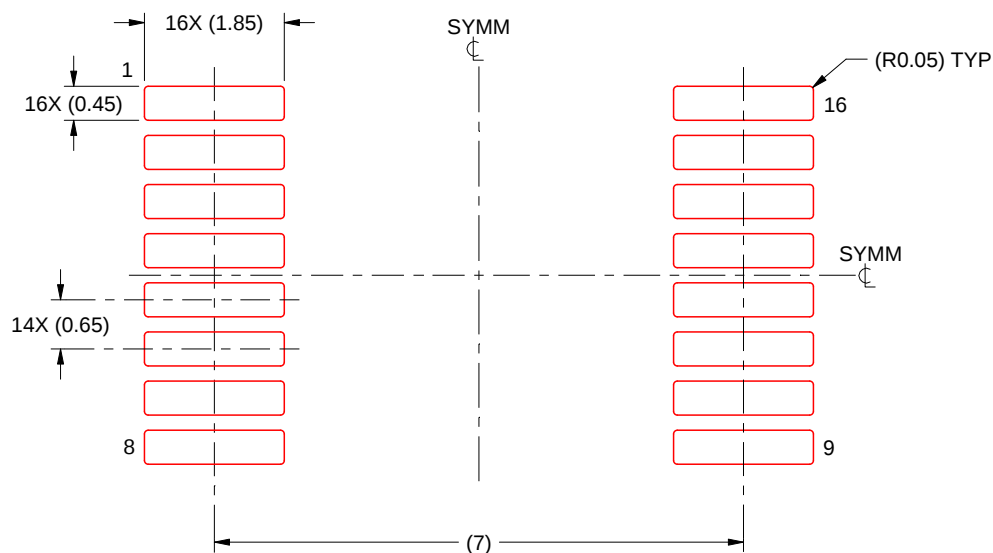
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

EXAMPLE BOARD LAYOUT

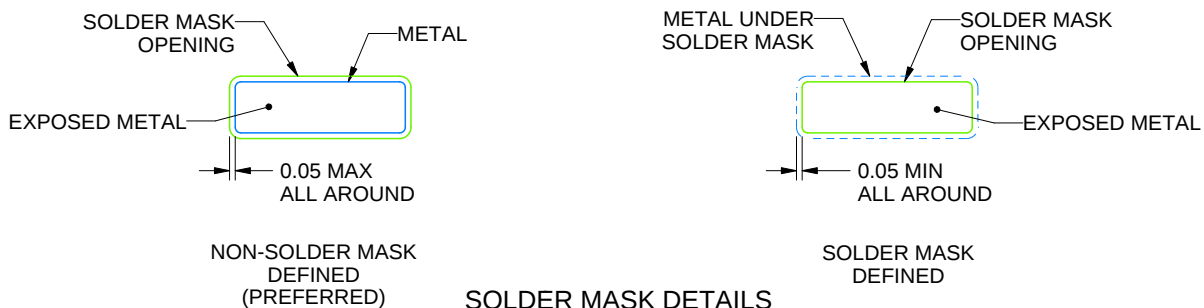
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



PACKAGE OUTLINE

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



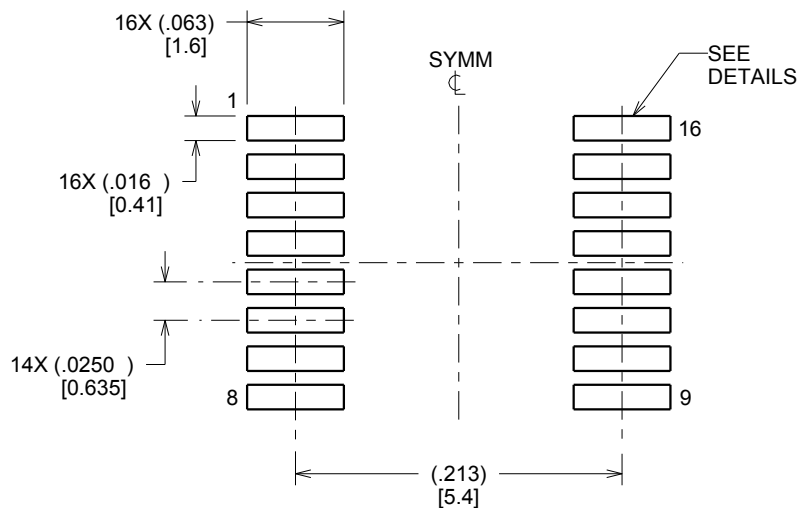
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 inch, per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MO-137, variation AB.

EXAMPLE BOARD LAYOUT

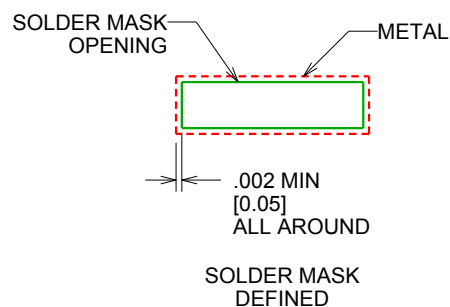
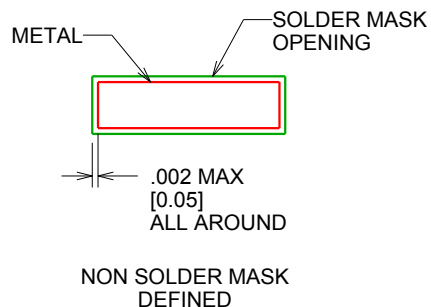
DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4214846/A 03/2014

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

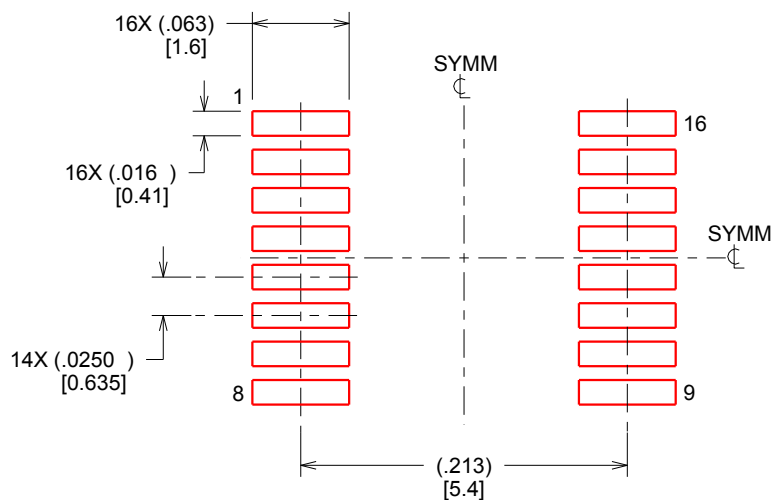
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.127 MM] THICK STENCIL
SCALE:8X

4214846/A 03/2014

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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